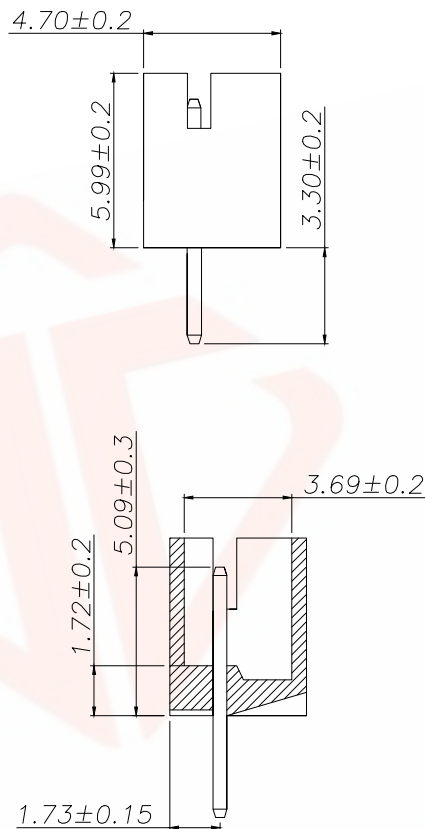
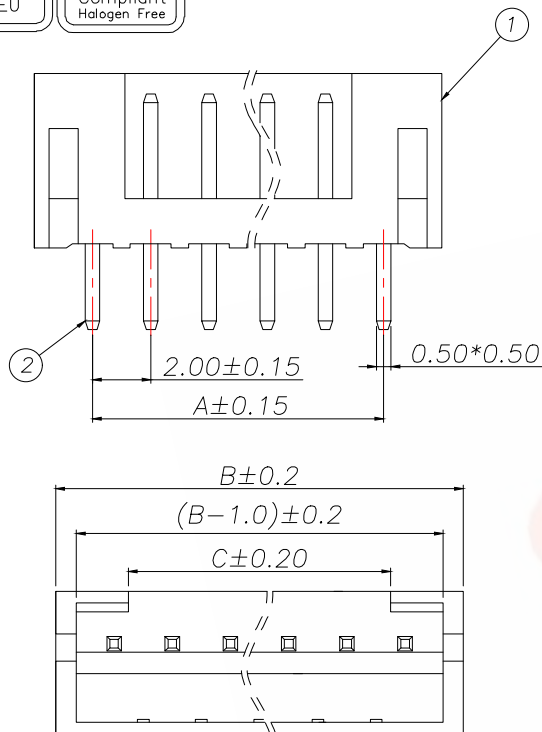


SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

1. 塑件材料: PA66(UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻: $\leq 10\text{m}\Omega$
4. 绝缘电阻: $>100\text{M}\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 2.0A AC DC
7. 耐压: 能承受 1000V AC/Minute
8. 工作温度: $-25^{\circ}\sim+85^{\circ}$
9. 可焊性试验: 浸锡面积 $\geq 95\%$ 温度 $235\pm 5^{\circ}$, 时间 2.5 ± 0.5 秒
10. 铅和镉等六大有害物质含量要符合环保要求。

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN

Part No	Pin	A	B
APH-B2B-11	2	2.00	6.00
APH-B3B-11	3	4.00	8.00
APH-B4B-11	4	6.00	10.00
APH-B5B-11	5	8.00	12.00
APH-B6B-11	6	10.00	14.00
APH-B7B-11	7	12.00	16.00
APH-B8B-11	8	14.00	18.00
APH-B9B-11	9	16.00	20.00
APH-B10B-11	10	18.00	22.00
APH-B11B-11	11	20.00	24.00
APH-B12B-11	12	22.00	26.00
APH-B13B-11	13	24.00	28.00
APH-B14B-11	14	26.00	30.00
APH-B15B-11	15	28.00	32.00
APH-B16B-11	16	30.00	34.00
APH-B17B-11	17	32.00	36.00
APH-B18B-11	18	34.00	38.00
APH-B19B-11	19	36.00	40.00
APH-B20B-11	20	38.00	42.00

2	端子Contact	黄铜	N*1	电镀(锡): 整个表面镀底镍 30u"MIN, 再镀锡80u"MIN
1	基座Wafer	PA66(UL94V-0)	1	白色
序号	名称	材料	数量	备注

TOLERANCE		 深圳聚兴泰电子科技有限公司 Shenzhen Juxingtai Electronic Technology Co., Ltd				
X.X ±0.20	X.* ±10°	PART NO.		TITLE:		
.XX ±0.10	.X.* ± 8°	APH-BXB-11		PH2.0MM 直针		
.XXX ±0.05	.XX.* ± 5°	DESIGN: Ethan		MANUFACTURE DWG		
UNITS	mm					
MATERILA	— — —	CHED: Olvia			SCALE	SHEET
FINISH	— — —	APPD: Ava				
				N:A	1/1	